

WSK063

半导体晶圆切片机

WSK063 SiC slicing machine (slurry cutting)



技术规格参数 Specifications and Technical Parameters

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| 工件 workpiece | |
| 横断面 cross section | ≤Φ330mm |
| 长度 length | 2×300mm; 1×600mm |
| 厚度 thickness | 0.2-2.0mm (可按调整制程 set adjustable manufacturing process) |
| 切割速率 cutting rate | |
| 线速度 linear velocity | 最大 max 30m/s 速率 rate 可以设定 can set |
| 快速移动 fast move | 200mm/min |
| 工作行程 working stroke | 最大 MAX.385mm |
| 钢线 wire | |
| 芯线径 diameter of core wire (external diameter) | 0.055-0.400mm |
| 钢线长度 length of wire | 按线轮而定 according to wire wheel |
| 钢线方向 direction of wire | 前进或后退切割 forward or backward/double directional cutting |
| 预先张力 pre-tension | 最大 50N (端部线径而定) max. 50N (according to diameter of wire) |
| 导轮 guide wheel | |
| 直径 diameter | Φ192mm |
| 宽度 width | 62mm |
| 个数 number | 3 |
| 主机功率 main motor power | 最大 max. 3×30KW |
| 轴距 (左右) wheelbase (left & right) | 540mm |
| 轴距 (上下) wheelbase (up & down) | 150mm |
| 钢线偏向滚轮 offset roller | |
| 直径 diameter | 160mm |
| 个数 number | 2×3(0) |
| 卷绕线盘 winding coil | |
| 卷绕轴工作高度 working height of winding shaft | 135mm |
| 卷绕线盘 winding coil | WSK0235-2, 3, 4, 1 |
| 卷绕线盘在轴上的位置 winding coil on shaft position | 1, 2, 3, 4, 1 |
| 切割液供应 cutting compound supply | |
| 切割液容量 capacity of cutting tank | 300L |
| 切割液温度控制 temperature control of cutting fluid | 可设恒温或温度 optional preset temperature 20/25℃ |
| 泵浦流量 pump flow rate | 最大 MAX. 12000L/h (可调) 使用流量监测并显示 adjustable measure with flow meter and display |
| 冷却液入口温度 inflow temperature of cooling water | 15℃±1℃ |
| 电气系统 electrical system | |
| 供货商 supplier | 西门子 (Siemens) |
| 操作界面 operation panel | 工业触摸屏 industrial screen (5) |
| 外观尺寸及总重量 outline dimension and total weight | |
| 长度 length | 4470mm |
| 宽度 width | 2170mm |
| 高度 height | 3500mm |
| 总重量 total weight | 约 13000kg |

设备用途和特性

- 本机广泛应用于半导体行业用于半导体晶圆的切片，是半导体行业硅片加工的主要配套设备。硅锭横断面最大为Φ330mm，切片厚度最小为0.2mm，必须调整制程，一次装夹最大可切片达(300×230)片，是半导体硅片生产厂家的优选设备。
- 本机特点：
- 1、两个钢线导轮驱动，收(放)线驱动，及收(放)线的排线驱动，均采用伺服驱动，与工件同步。
- 2、钢线张力的检测控制也通过伺服电机驱动(恒张力)。
- 3、工件进给由伺服电机通过滚珠丝杆拖动，进给量的大小与钢线的引导速度相匹配。
- 4、切削液的搅拌与输送。切削液管道通过热交换器达到恒温，及计量器计量，与切片速度同步。
- 5、本机床为高新技术集中的产品。

Applications and structural features

- the machine is used for cutting semiconductor bar, which is main matched processing equipment. The max dimension of cross section Φ330mm, the minimum thickness of section 0.2mm, adjust processing procedure, it may cut 1300×230 slices at one clamp. The optimized equipment for semiconductor manufacturers.
- features:
- two wire guide wheel drive, spool drive, and wire guide wheel drive, all use servo drive and synchronous with workpiece.
- detection control of wire tension also be controlled by motor (constant tension).
- workpiece feed is driven by servo motor through ball screw feed rate is matched with guiding speed of wire.
- agitation and conveying of cutting fluid. Cutting fluid pipe can reach up constant temperature through heat exchanger, matching the slicing rate.
- this machine is an integrated high-tech product.